

# Status of the **ESS MEBT FC**



FC Team  
ESS-Bilbao  
Beam Instrumentation Group

October – 2016

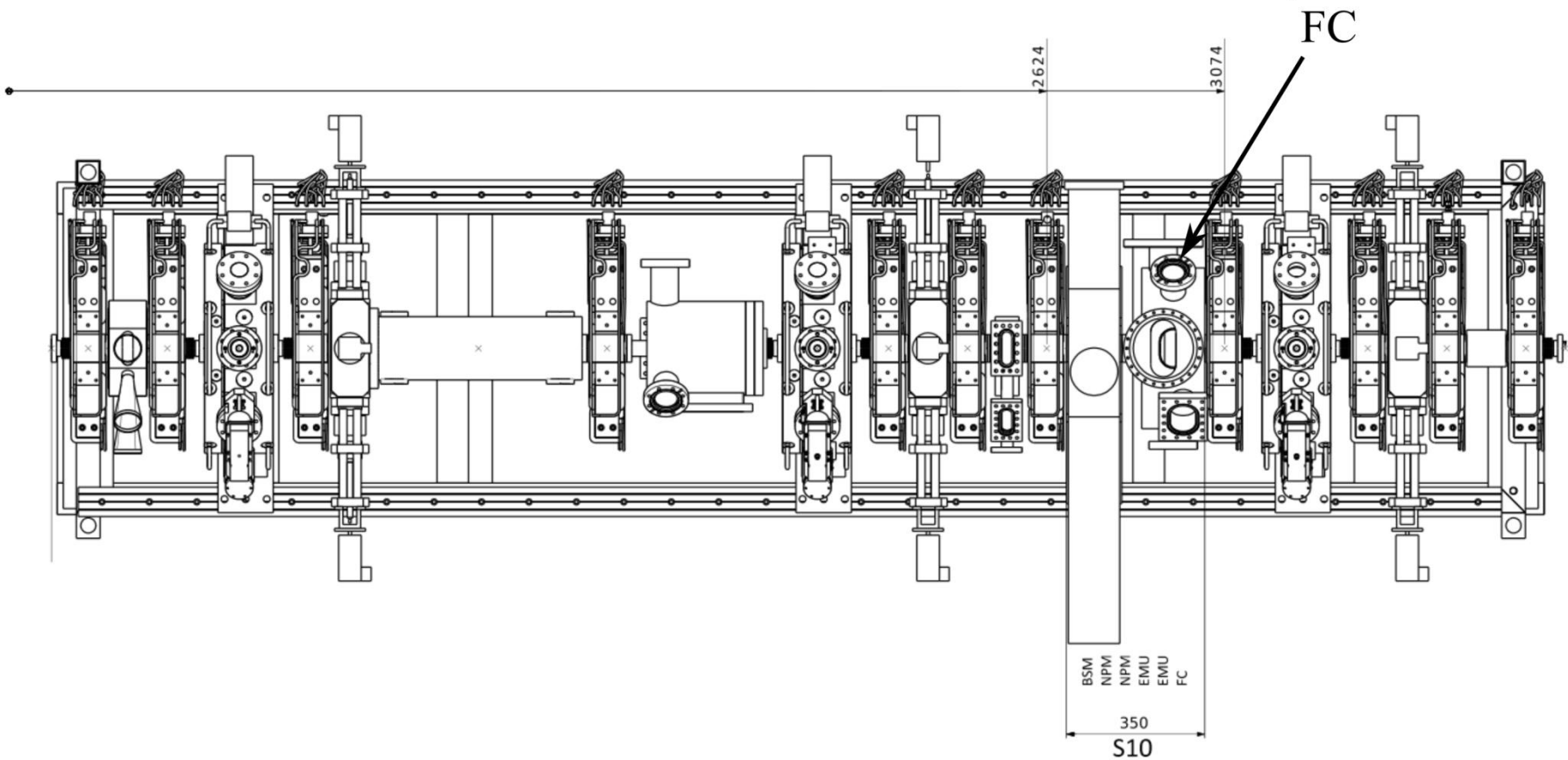
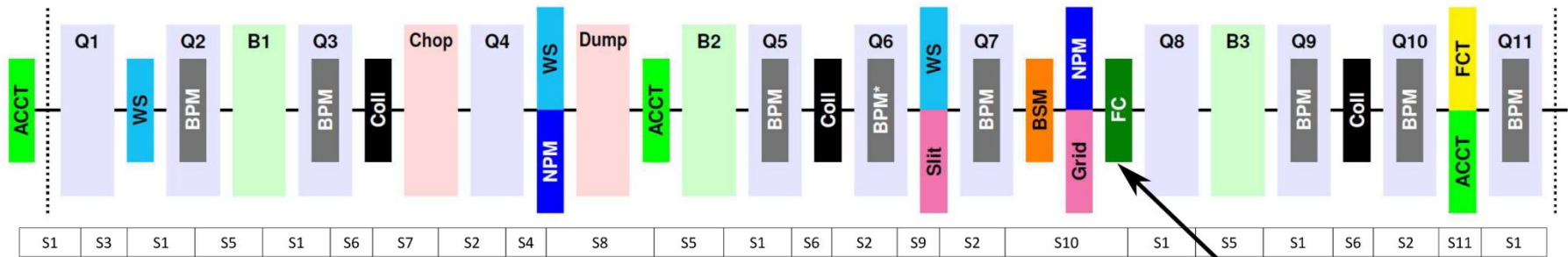
# Summary

- .Introduction
- .Conceptual Design
- .Mechanical Design
- .Signal Conditioning
- .EEE Integration & IOC
- .Conclusions

# Summary

- Introduction
- Conceptual Design
- Mechanical Design
- Signal Conditioning
- EEE Integration & IOC
- Conclusions

# ESS MEBT

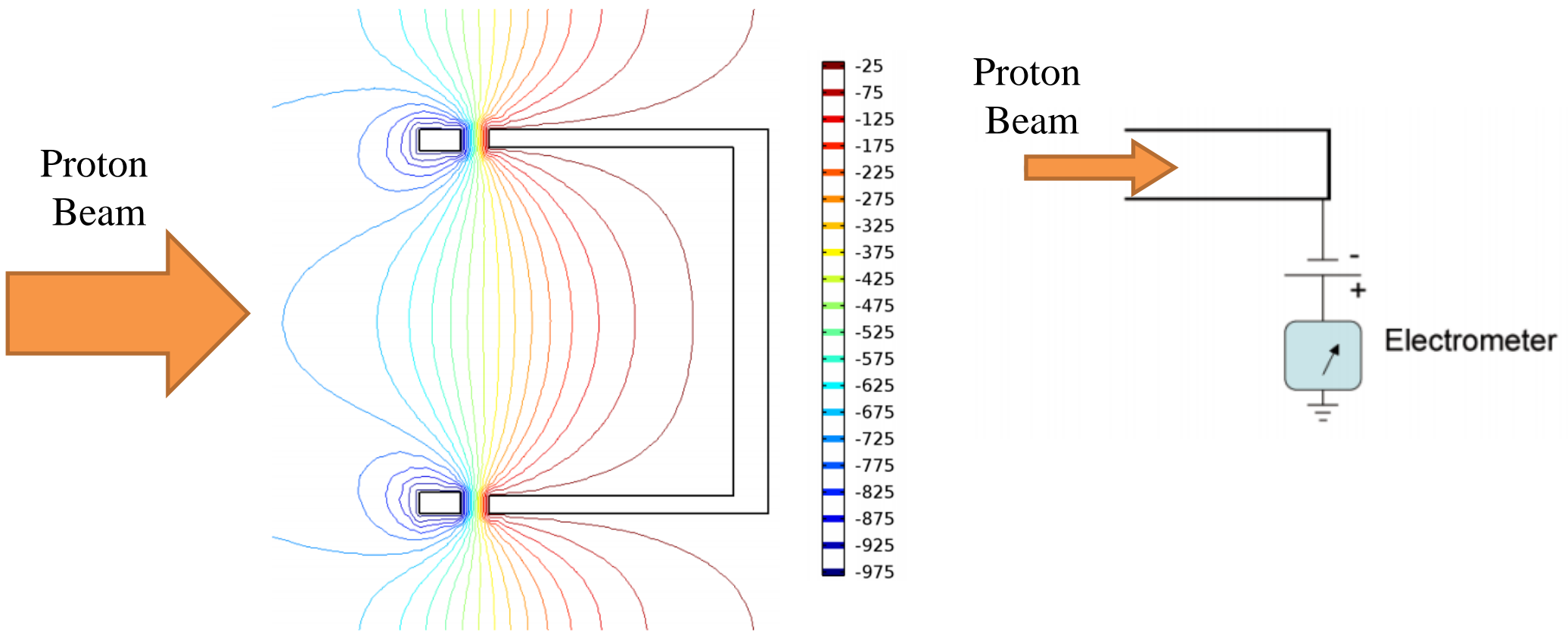


# ESS MEBT FC

- Beam Instrumentation is required in order to characterize beam current, size, emittance, etc
- The Faraday Cup purpose is to stop a pulsed proton beam to measure the total beam current.
- Faraday Cup is irradiated in Fast and Slow tuning modes.

Parameter	Value	
Proton Energy	3.63	MeV
Intensity	62.5	mA
Mode I: Fast Tuning	5 $\mu$ s - 14 Hz - 16 W	
Mode II: Slow Tuning	50 $\mu$ s - 1 Hz - 11 W	
Beam size	$\sigma_x$	2.48 mm
	$\sigma_y$	2.62 mm

# FC Scheme

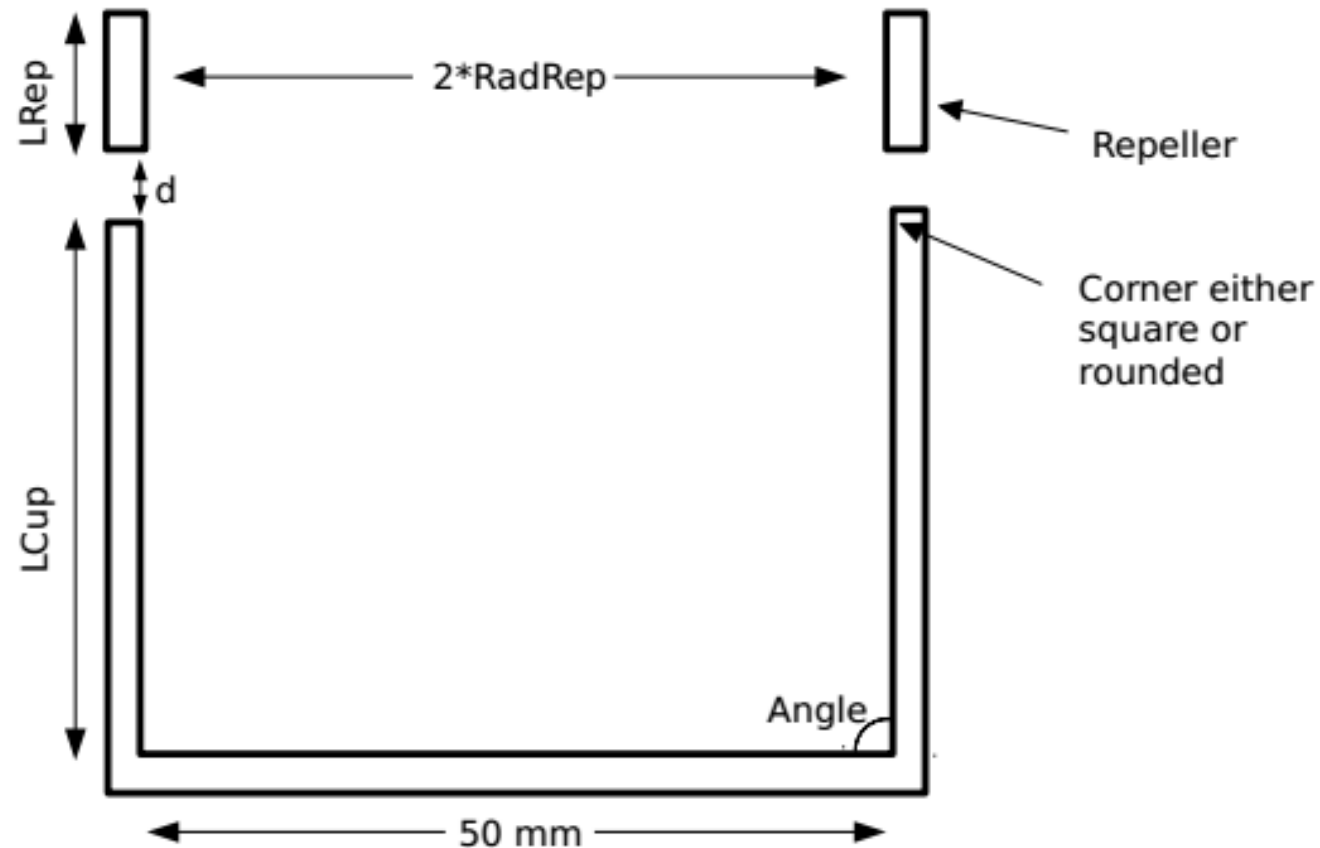


# Summary

- Introduction
- Conceptual Design
- Mechanical Design
- Signal Conditioning
- EEE Integration & IOC
- Conclusions

# Repeller

- Beam dynamics studies\* carried out to determine the effect of several geometric parameters on the FC repelling ability.

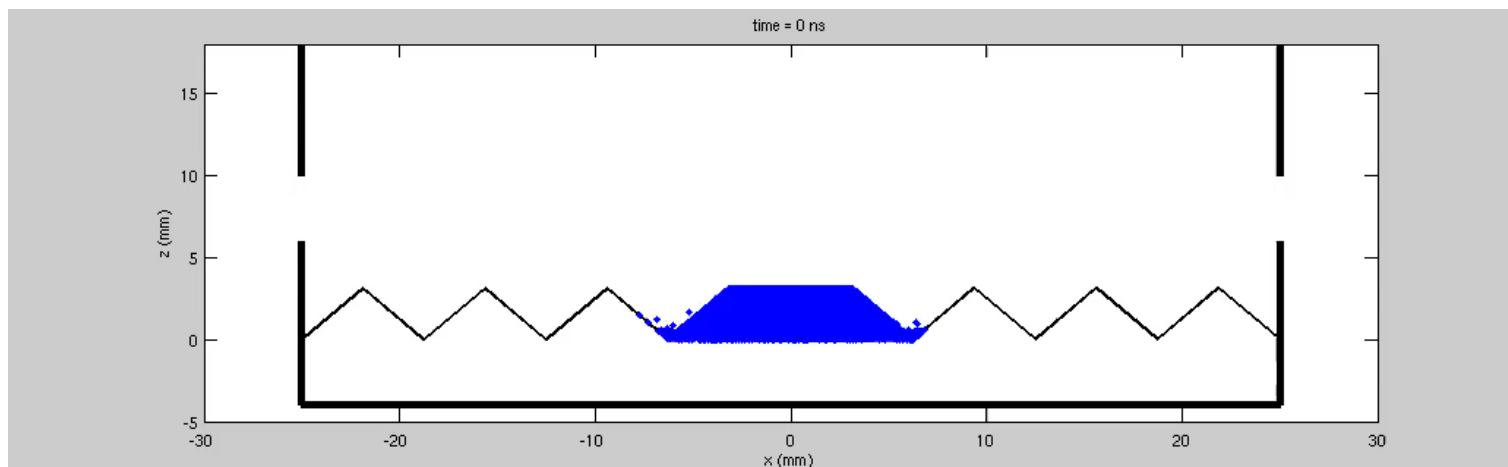


(\* Presented at the Beam Instrumentation Forum I (Lund, February 2016)



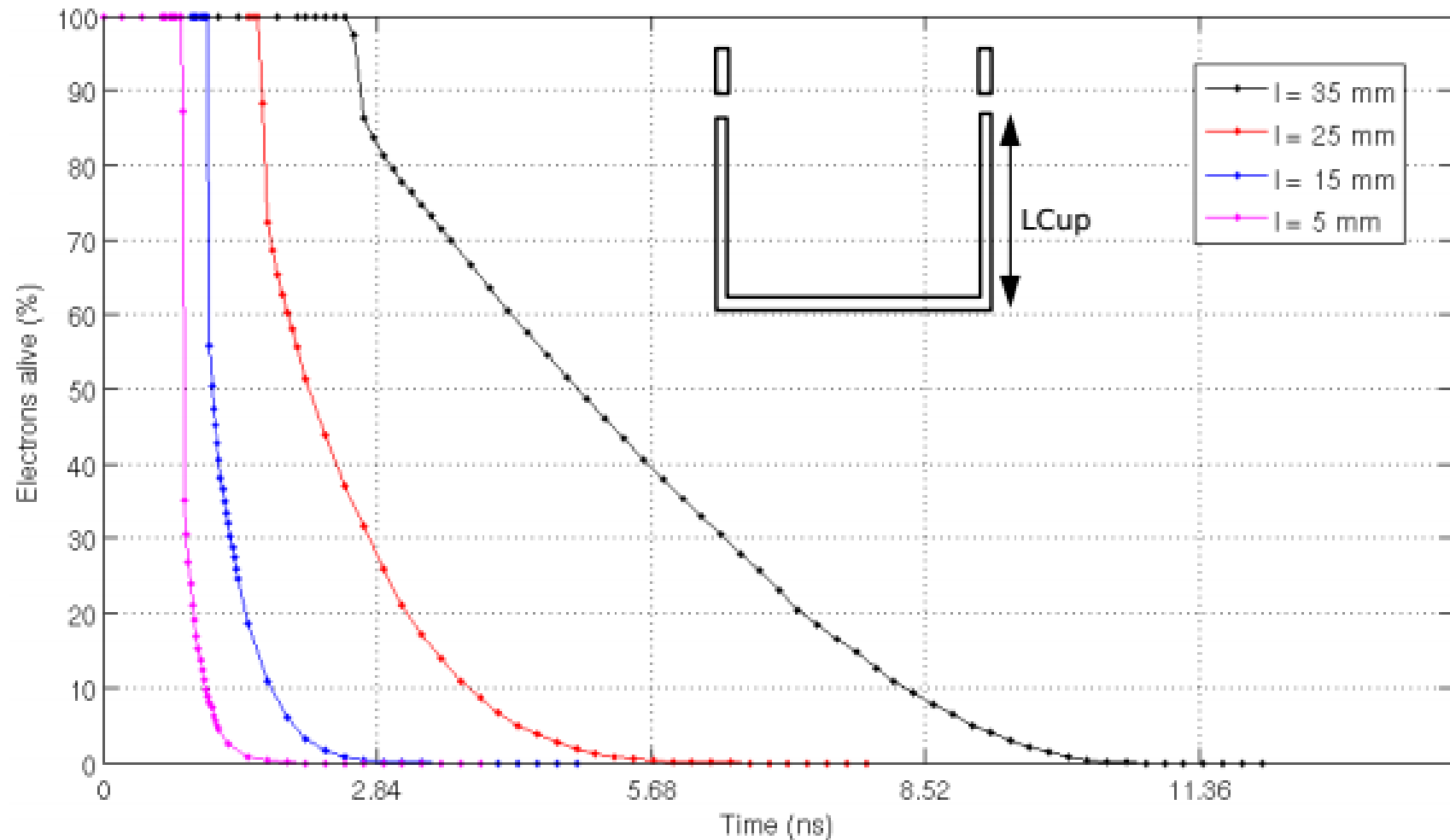
# Repeller Analysis

- Electrostatic field simulations made with Comsol, particle dynamics studies performed with GPT.
- Considerable effort to create an accurate secondary electron beam (beam footprint, collector angle, emission angle probability and energy distribution, etc).
- The video shows a typical simulation, observing the electron trajectories, impact position and recapture time.



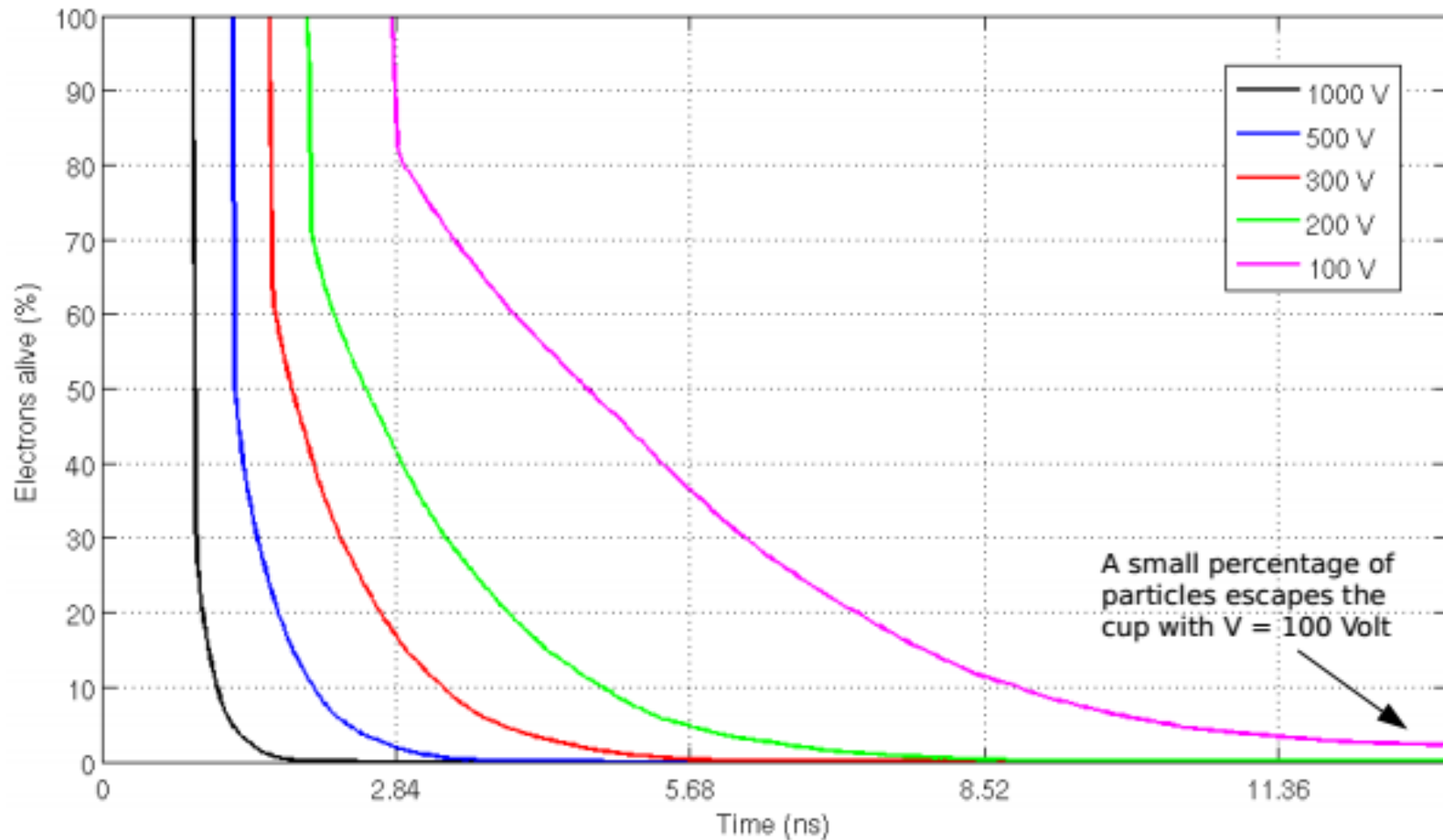
# Repeller Analysis

## Distance Collector-Repeller



# Repeller Analysis

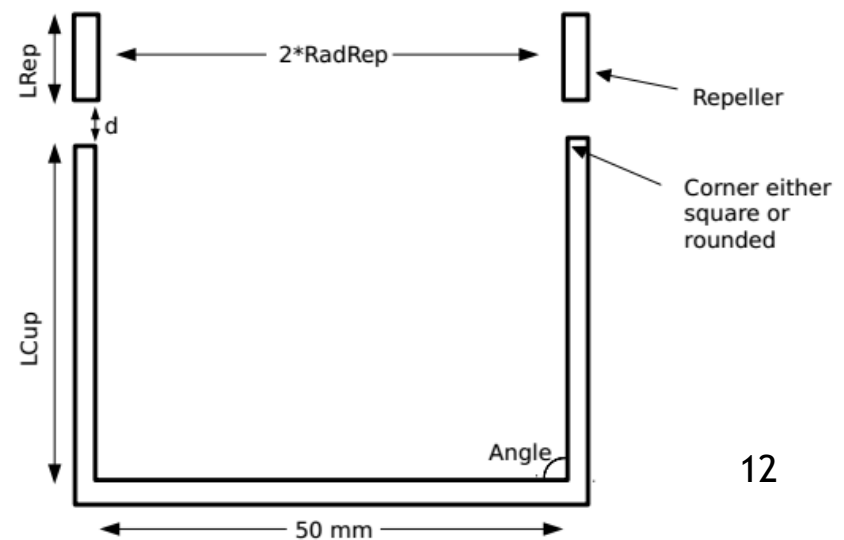
## Repeller Voltage



# Repeller Analysis

- Basic simulations indicate that we can achieve a 100% electron suppression in the Faraday Cup. Full recapture times typically take a few ns.
- A full recapture can also be achieved if the suppressor voltage is lowered down to 200 V, although the total capture time is obviously longer.
- The final design assumes:

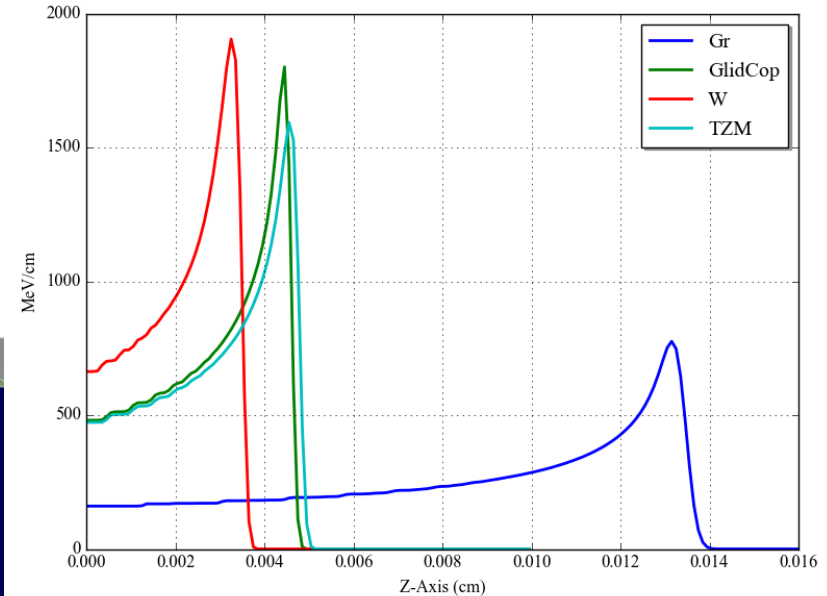
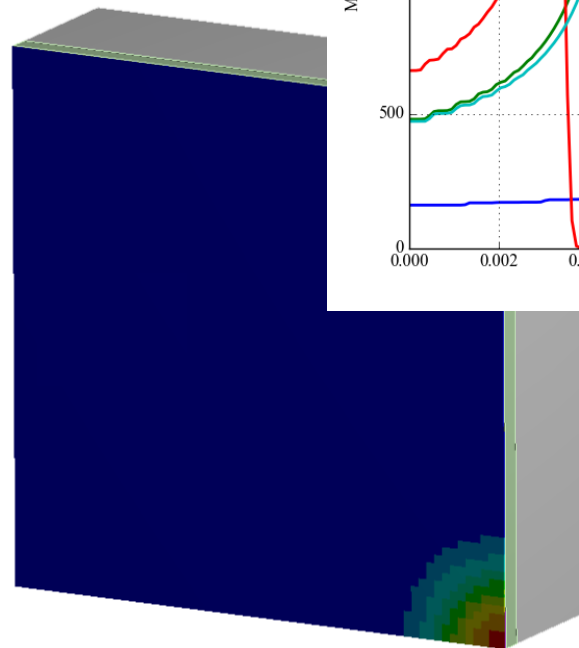
- Voltage: 1 kV
- LCup: 10 mm
- LRep: 10 mm
- d: 4 mm



# Thermomechanical effects

- Irradiation is highly concentrated in spots  $\sim$ mm and depths  $\sim$ 100  $\mu$ m. This leads to high temperatures and stresses during the transient (50  $\mu$ s).
- Graphite is in contact with refrigerated substrate to dissipate heat in the steady state.

Parameter	Value
Proton Energy (MeV)	3.63
Beam Current (mA)	62.5
Pulse duration ( $\mu$ s)	50
Pulse Energy (J)	11
Peak Power (kW)	227
Beam Sigma (cm)	0.25
Beam Spot (cm <sup>2</sup> )	0.4
Beam Current(mA/cm <sup>2</sup> )	159
Beam Current( $\mu$ C/cm <sup>2</sup> )	8.0
Stopping Power (MeV/cm)	775
Energy Deposition (MW/cm <sup>3</sup> )	123
Energy Deposition (kJ/cm <sup>3</sup> )	6



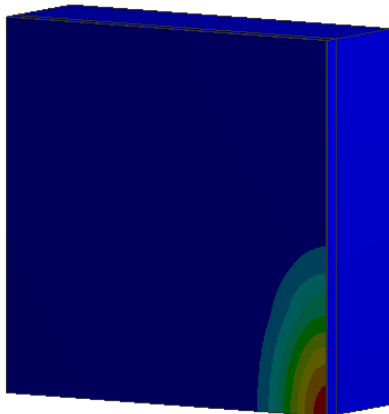
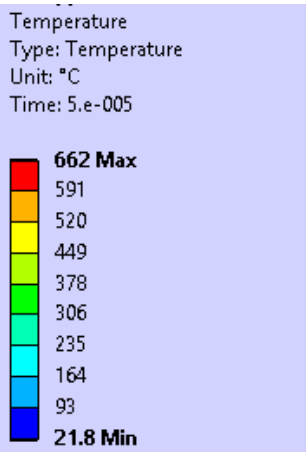
# Transient

- High temperatures and stresses are attained during the pulse (50  $\mu$ s).
- A criterion  $\sigma_{Max} \leq 2/3 \sigma_{Strength}$  is used.

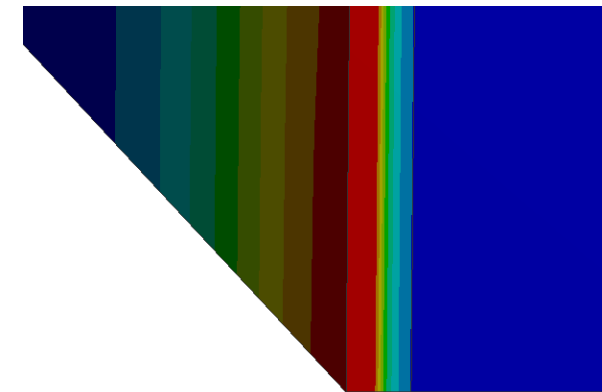
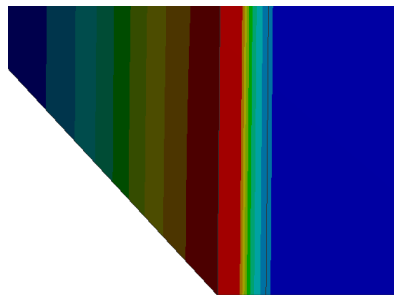
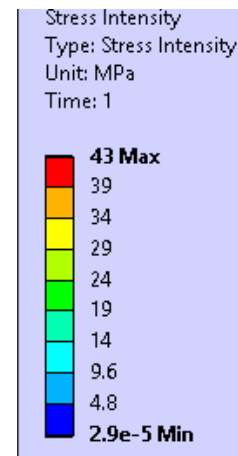
Mat. Limit	Graphite
Melt Temp. (K)	3773
Ult. Tensile Strength / Design Limit (MPa)	40 / 26
Ult. Comp. Strength / Design Limit (MPa)	125 / 83

Case	$I''$ ( $\mu$ C/cm <sup>2</sup> )	$\Delta T$ (K)	$\sigma_{Int}$ (MPa)	$\sigma_{Int}/\sigma_{Lim.}$
FC: 30°	4.0	640	43	51%

a) Temperature



b) Stresses

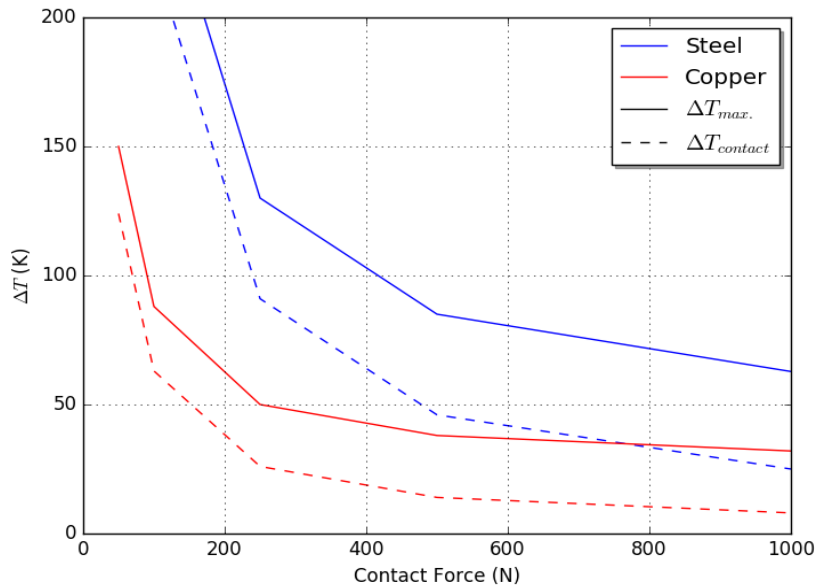


# Stationary State

- Thermal contact between graphite/insulator/steel body.
- Cooled by water channels in the FC body
- Dependant on contact conductivity, roughness and microhardness

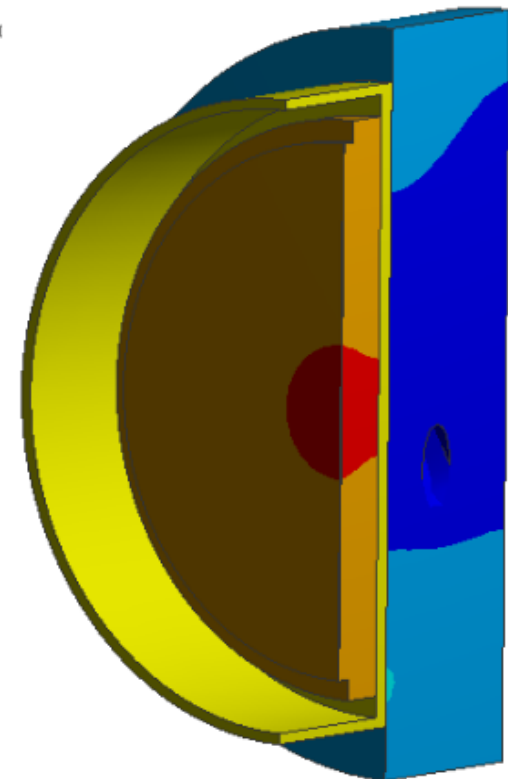
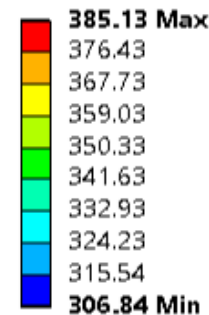
- $$h_c \cdot \frac{\sigma_c/m_c}{k_c} = 1.25 \cdot \left(\frac{P}{H_c}\right)^{0.95}$$

- Contact Pressure  $\sim 1$  MPa, Force 500 N
- Stationary state is attained in  $\sim 300$  s
- Low temperature gradient ( $< 100$  K)
- Low stresses ( $\sim 1$  MPa)
- Small Deformations ( $10-20 \mu\text{m}$ )



Steel - 500 N

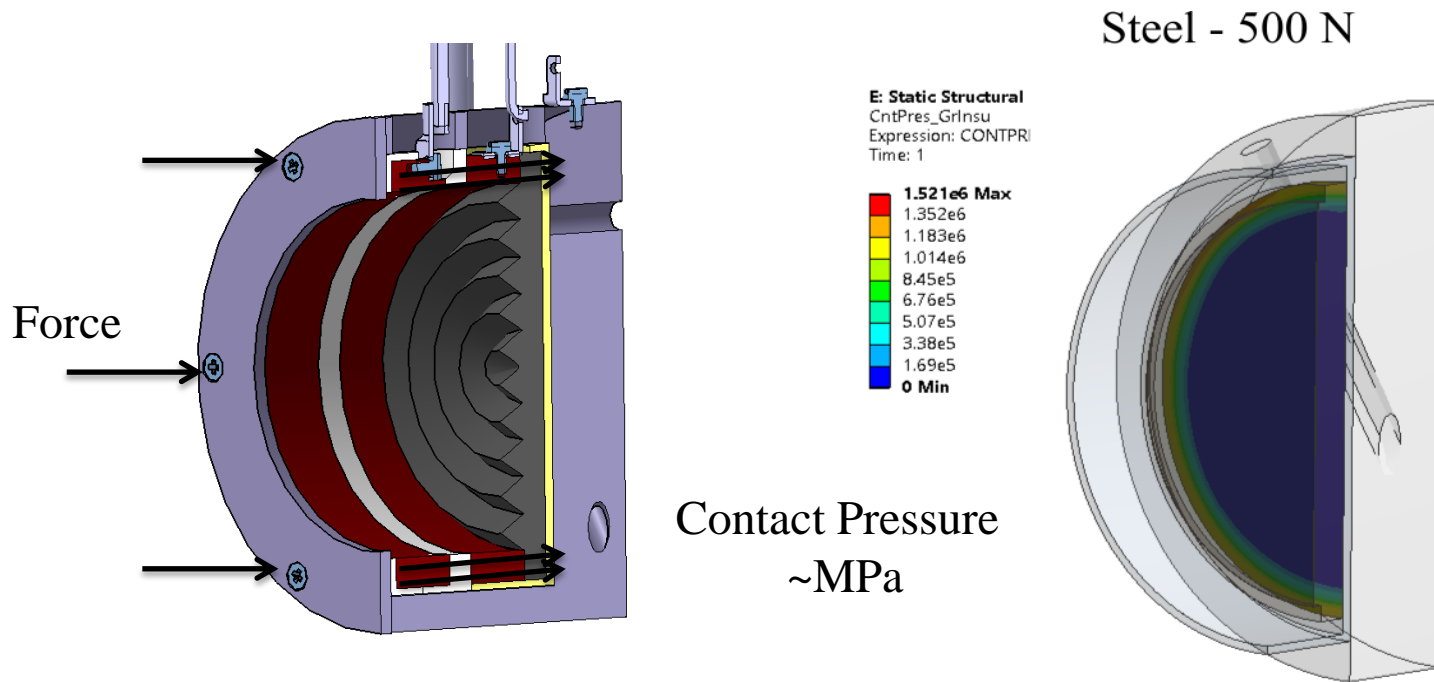
D: Steady-State Thermal  
Temperature  
Type: Temperature  
Unit: K  
Time: 1



# Stationary State

- We choose a steel substrate for a more simple manufacturing.
- Steel dissipates heat correctly if good thermal contact is applied, Force~500N.
- Thermal Contact is only effective where contact pressure is applied.

Component	Substrate	Contact Force (N)	Max. Temp. (K)	Max. Gr. Def. ( $\mu\text{m}$ )	Max. Gr. Stress (MPa)	Min. Gr. Stress (MPa)
FC	Steel	500	85	20	0.7	-1.8

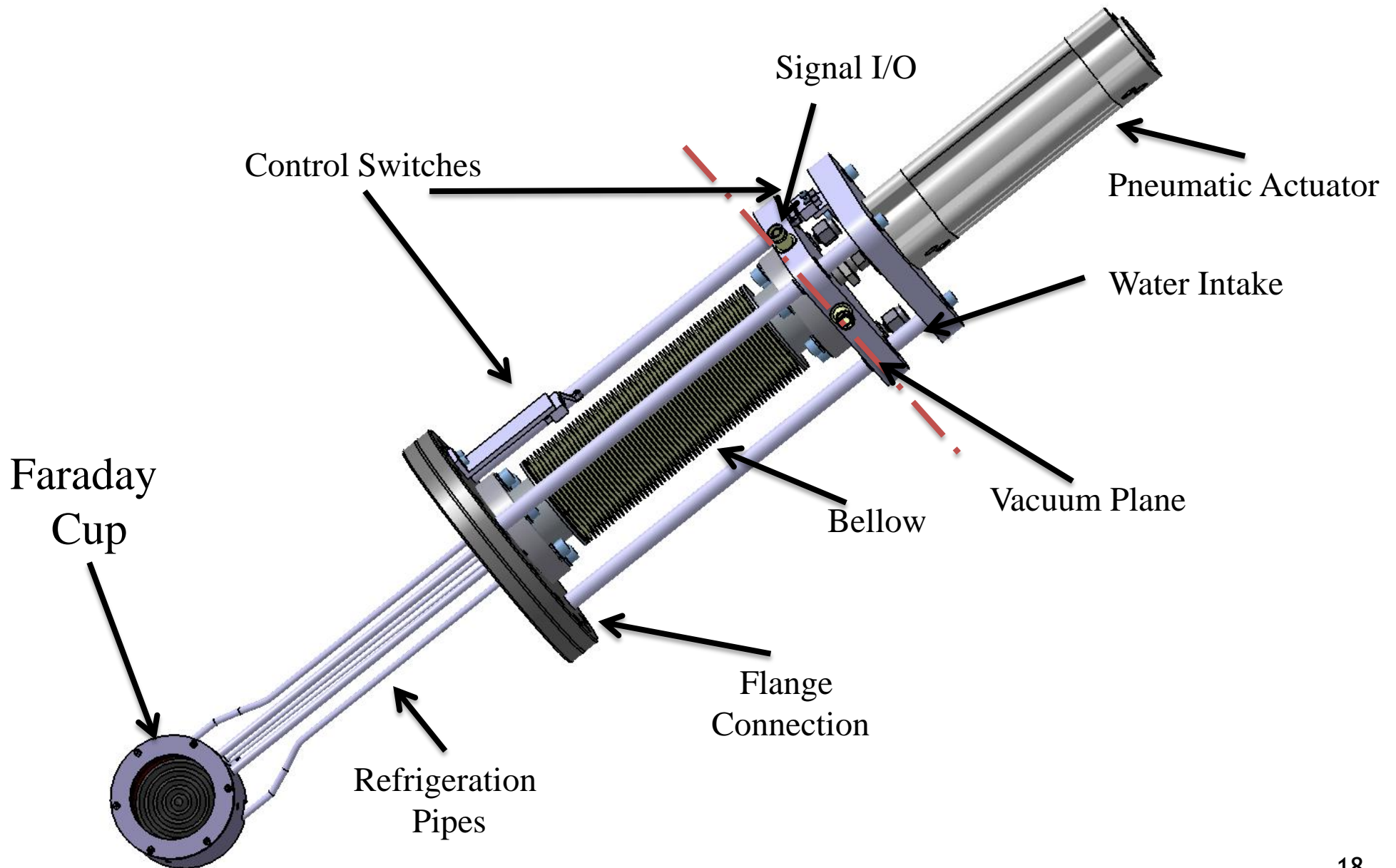




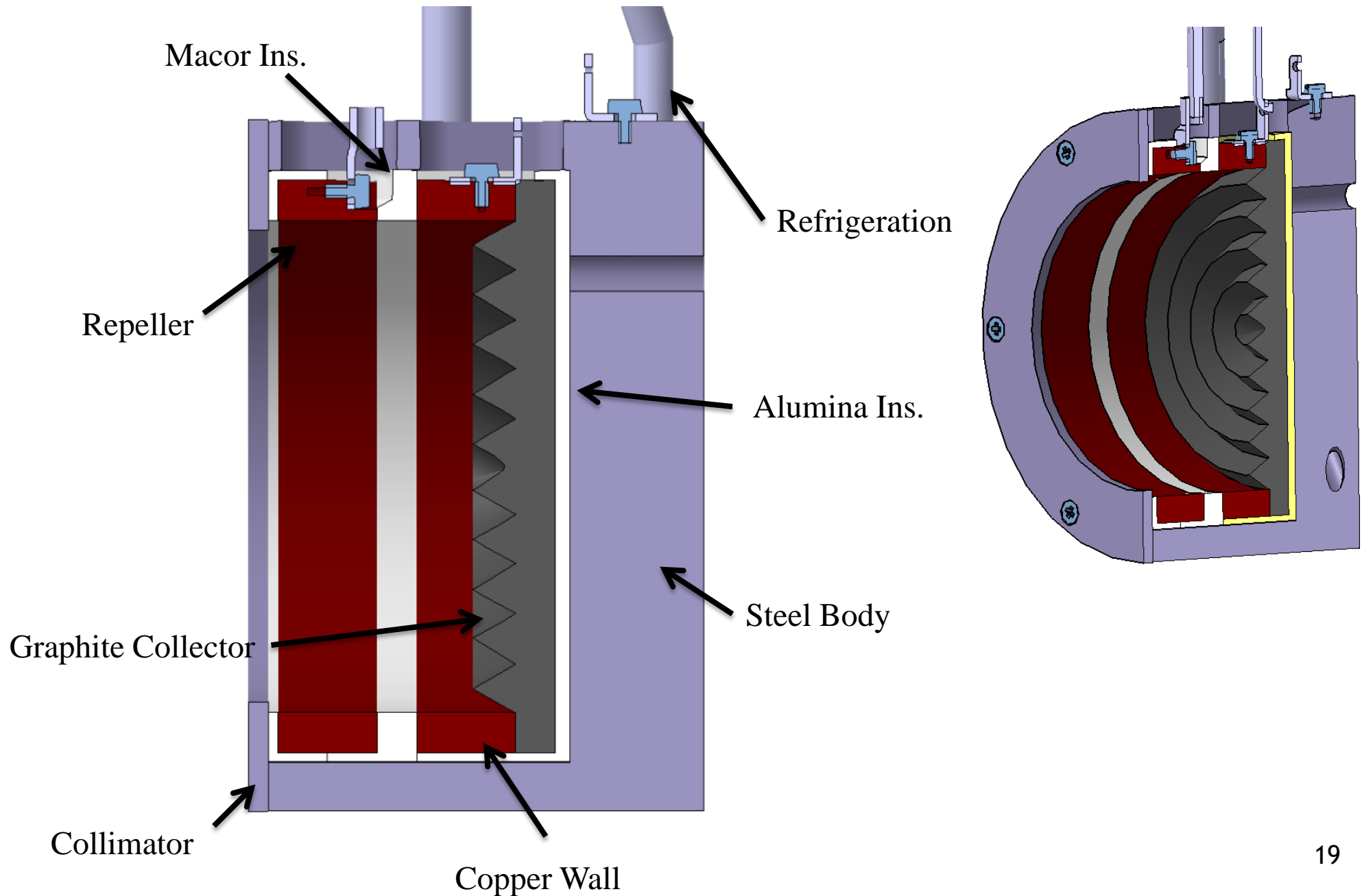
# Summary

- .Introduction
- .Conceptual Design
- .Mechanical Design
- .Signal Conditioning
- .EEE Integration & IOC
- .Conclusions

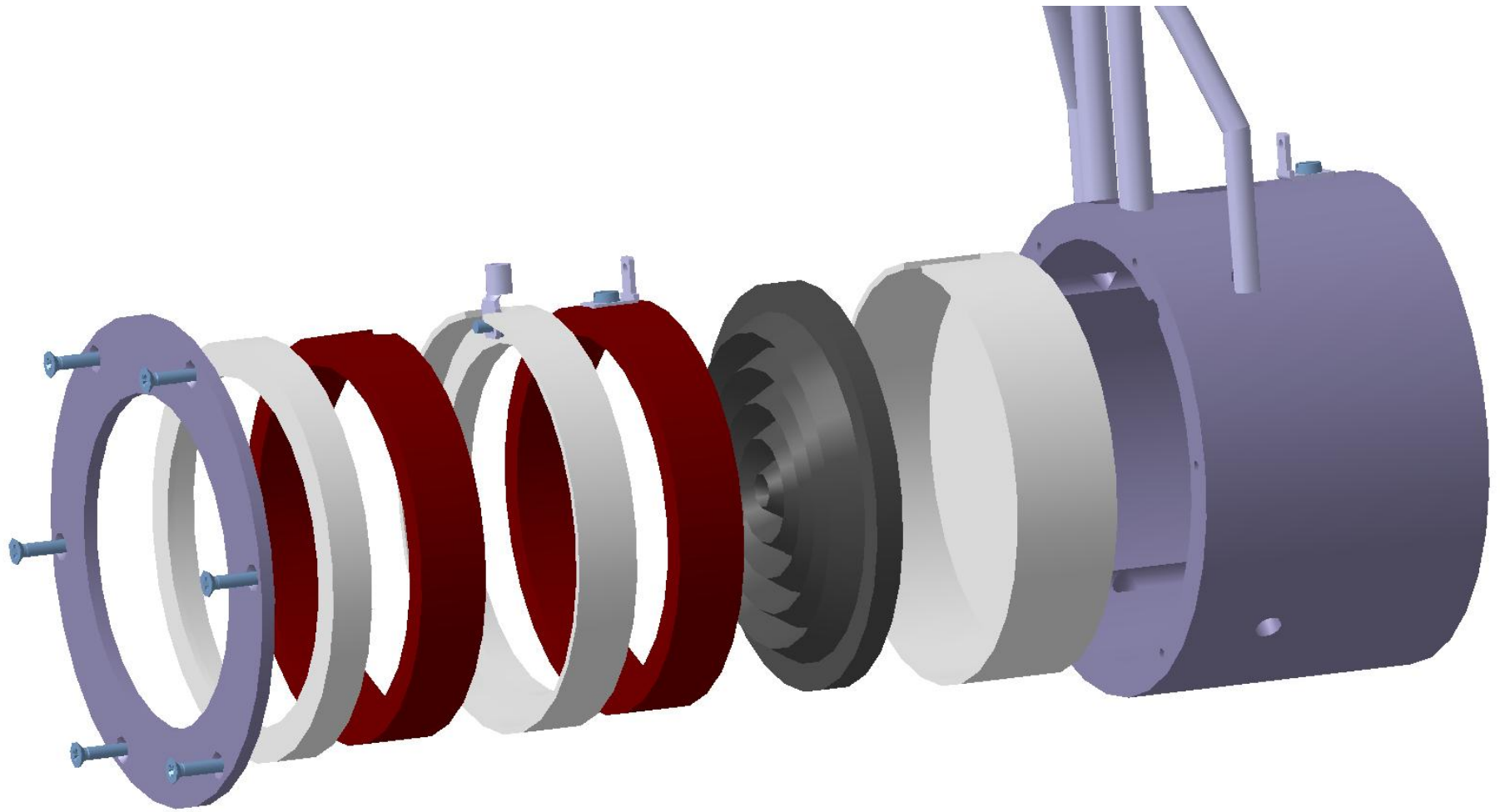
# Mechanical Design



# Mechanical Design



# Mechanical Design

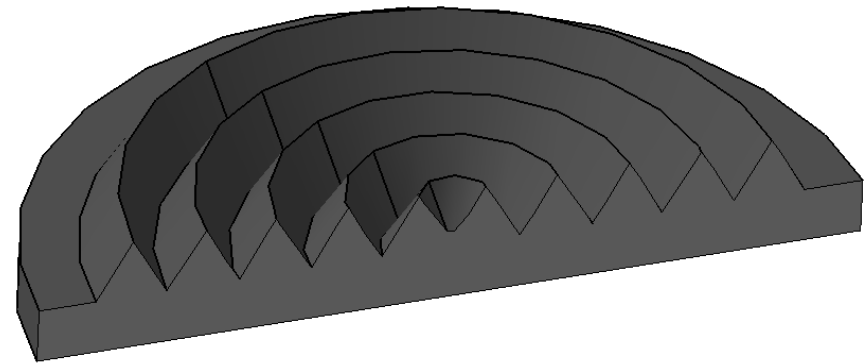
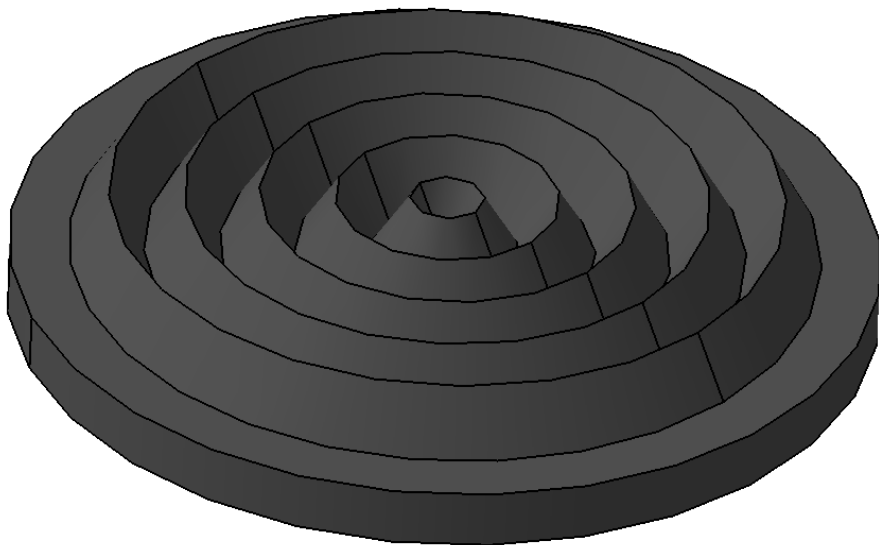
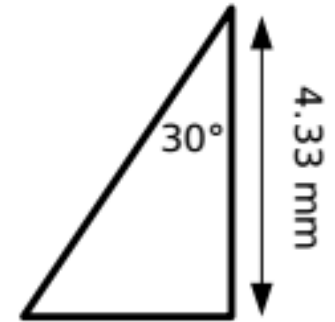
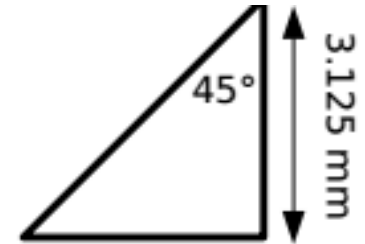


# Graphite Collector

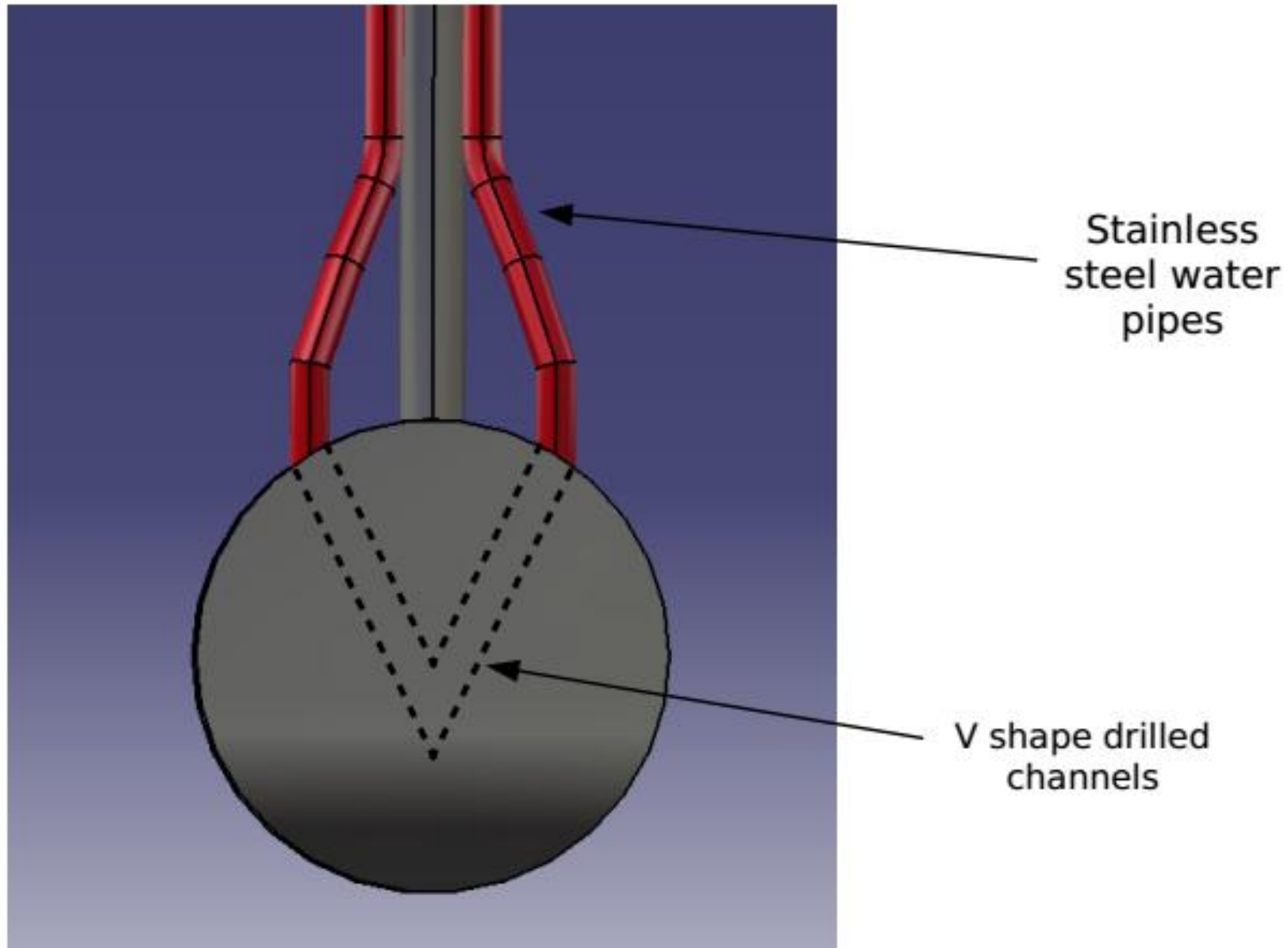
Graphite plate with indented surface for better performance under irradiation.

Plate of 58 mm diameter, 4 mm thickness and 4.33 mm sawteeth height.

Sawteeth with angles of  $30^\circ$

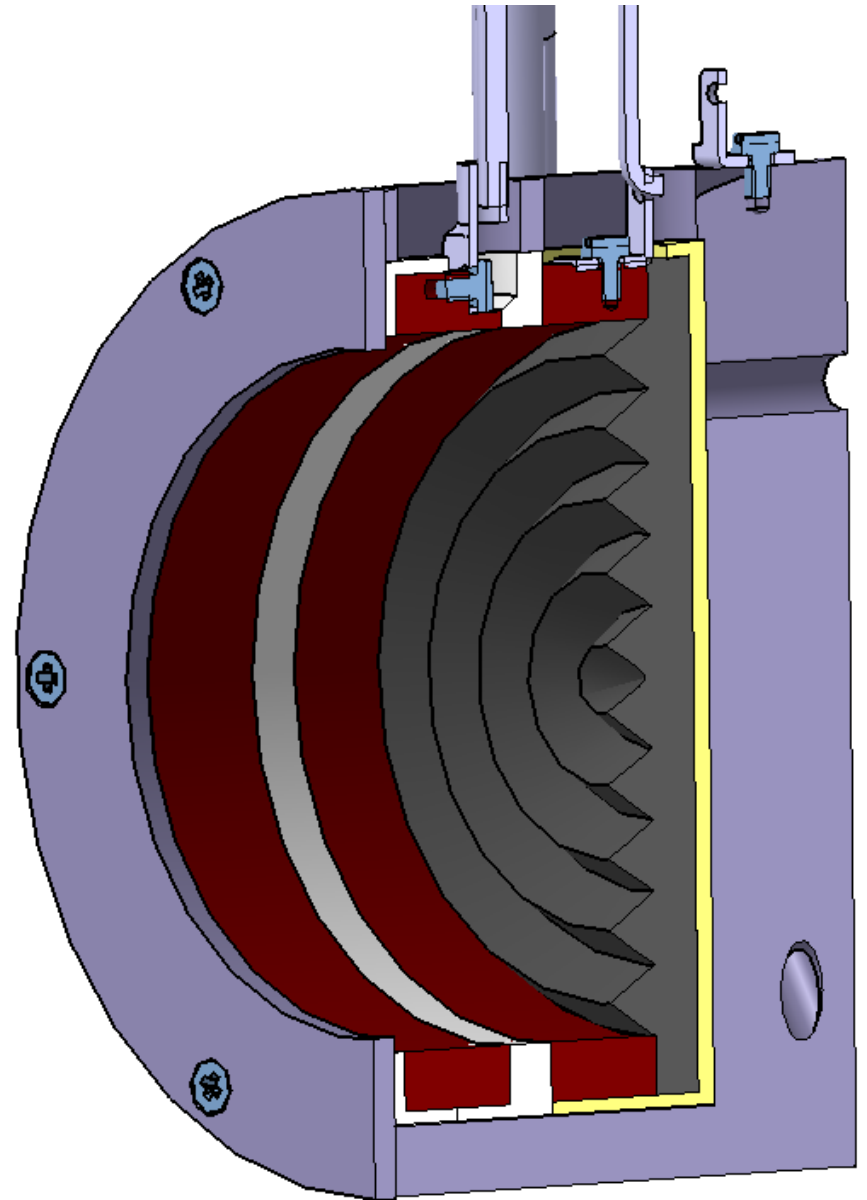


# Cooling



# Main Dimensions

- Nominal Diam.: 50 mm
- Width: 46 mm
- Ext. Diam.: 70 mm
- Collimator Diam.: 48 mm
- Actuator Stroke: 80 mm



# Summary

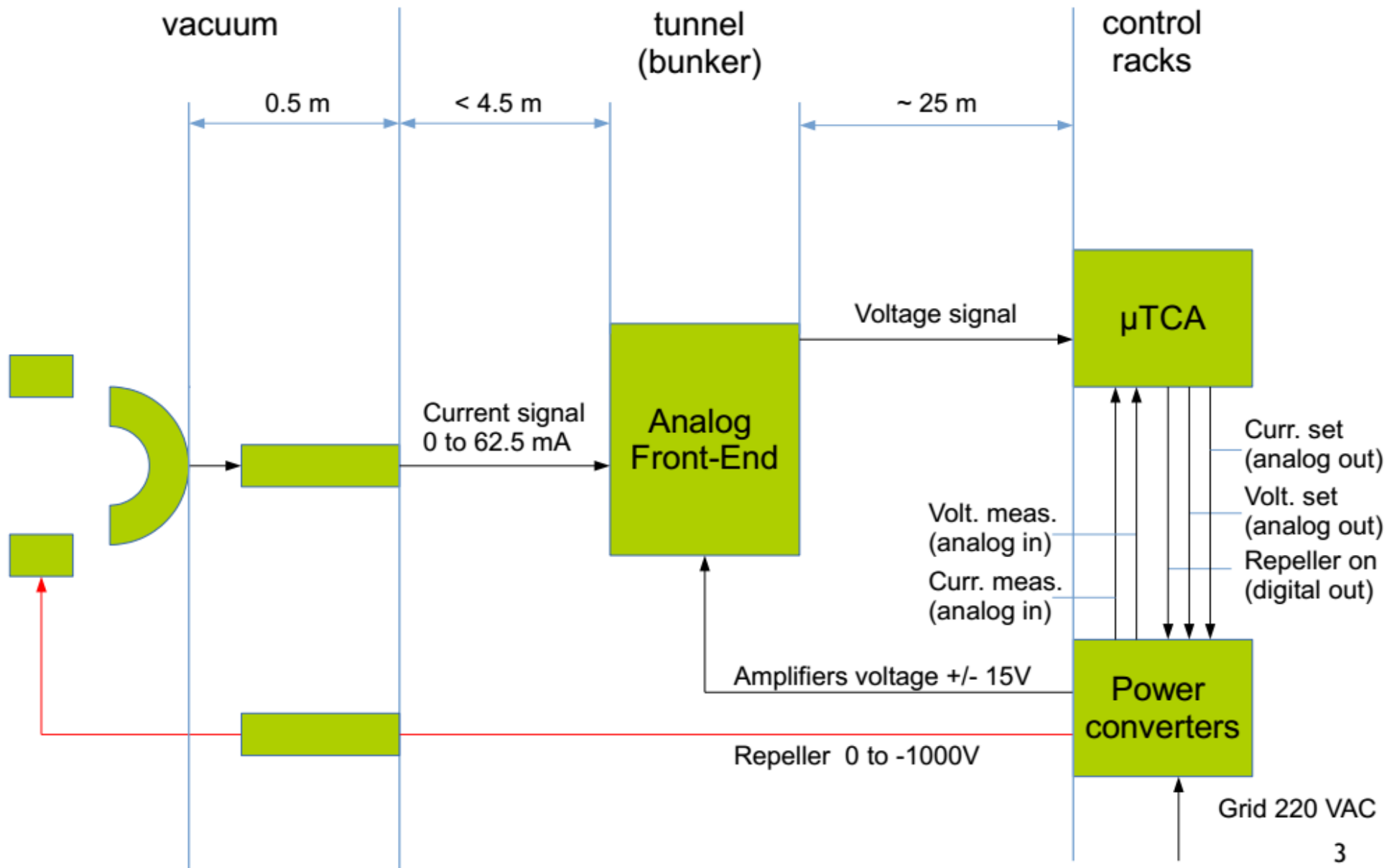
- .Introduction
- .Conceptual Design
- .Mechanical Design
- .Signal Conditioning
- .EEE Integration & IOC
- .Conclusions



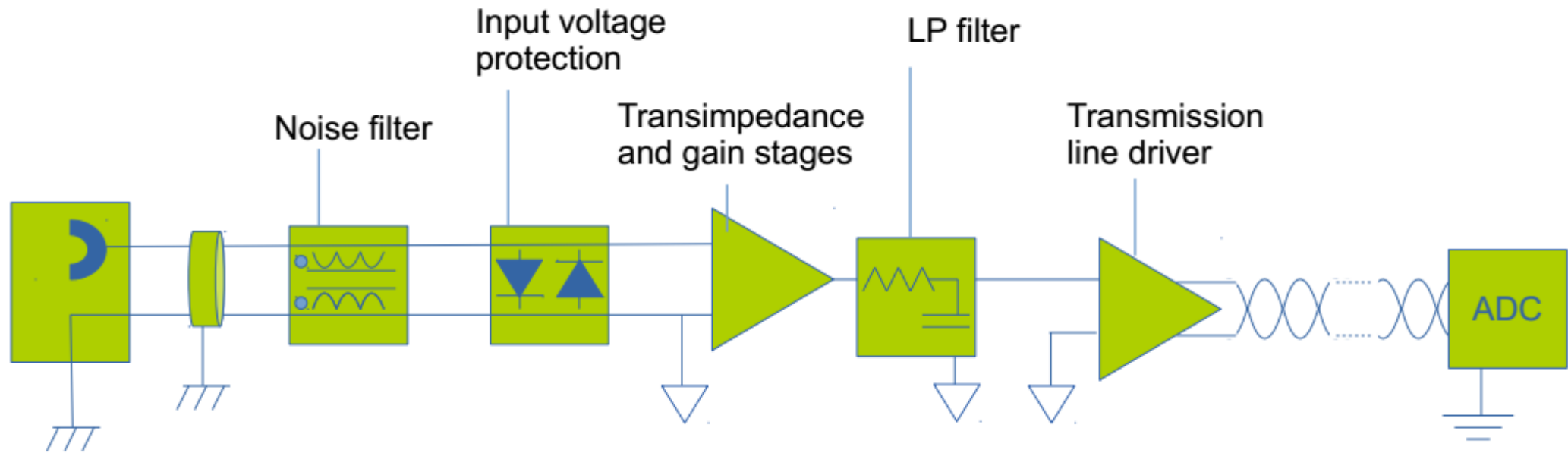
# Design Parameters

<i>Beam peak current</i>	62.5 mA
<i>Dynamic range</i>	10
<i>Beam mode 1</i>	50 us & 1 Hz
<i>Beam mode 2</i>	10 us & 14 Hz
<i>Sample frequency</i>	$\geq 2$ MHz
<i>Total measurement error</i>	$< 0.1$ mA
<i>Measurement precision</i>	$\sigma < 0.01$ mA
<i>Output voltage range:</i>	+/-10 V
<i>ADC Resolution</i>	16 bits
<i>Remotely controlled power supply</i>	0 to 1000V (negative)

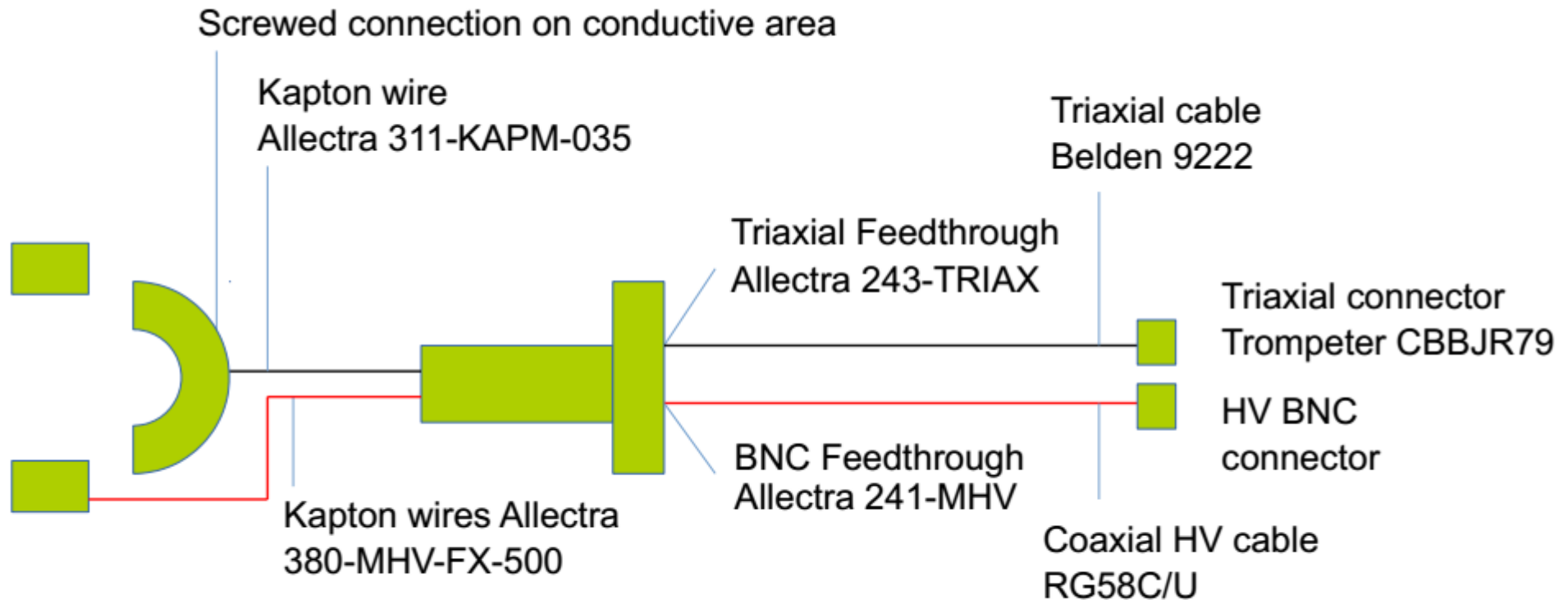
# General Scheme



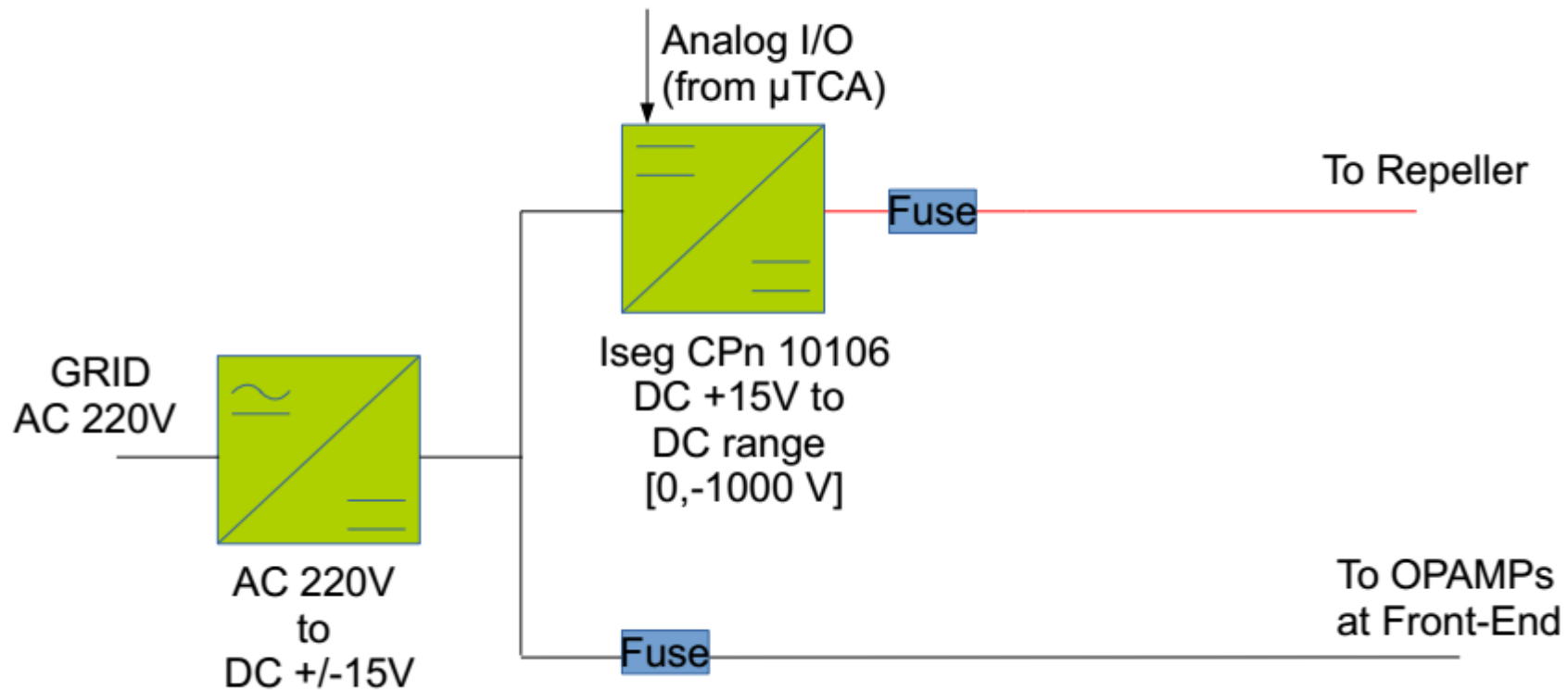
# Analogue Front End



# Cabling and Connections



# Power converters enclosure

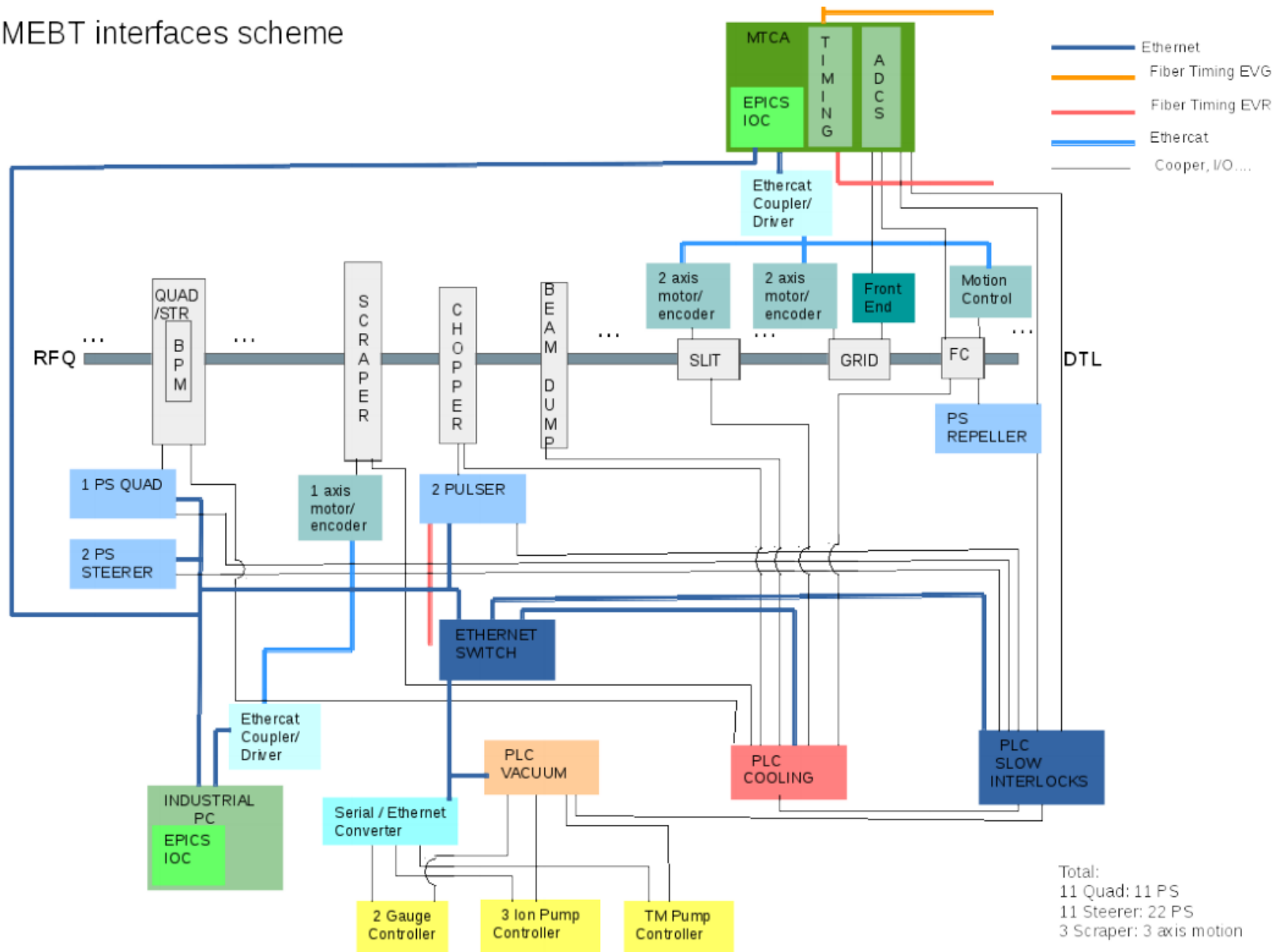


# Summary

- .Introduction
- .Conceptual Design
- .Mechanical Design
- .Signal Conditioning
- .EEE Integration & IOC
- .Conclusions

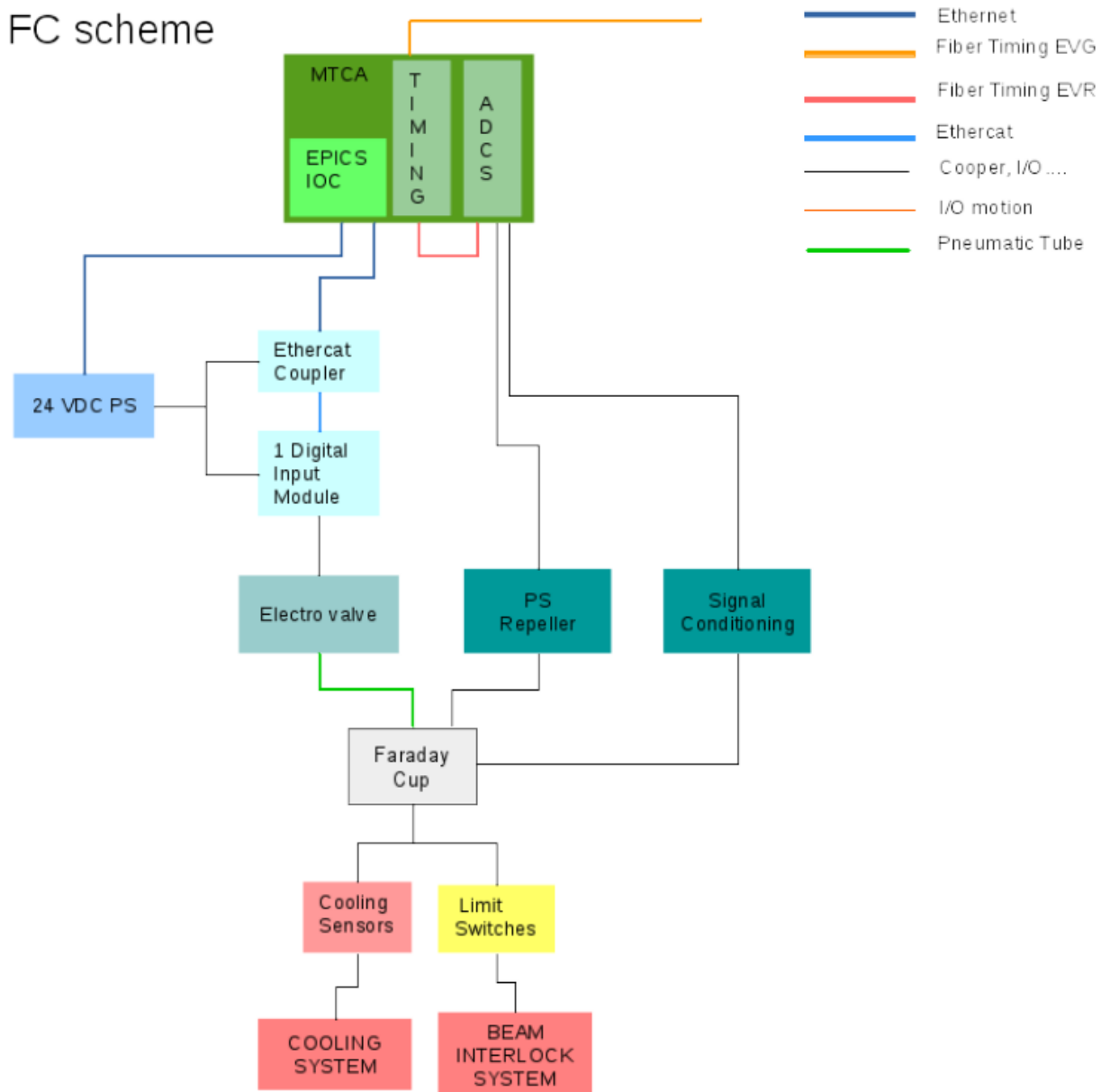
# HW Description

MEBT interfaces scheme



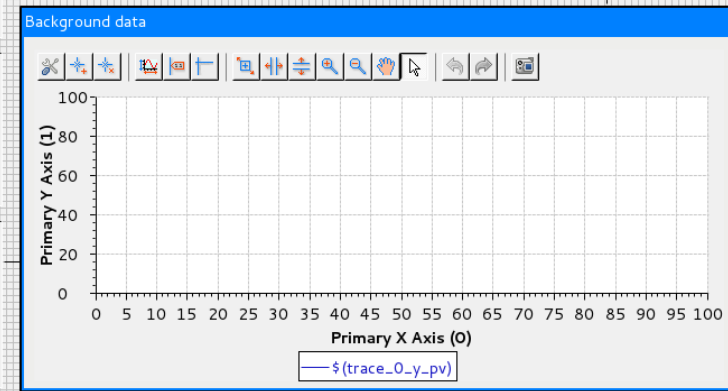
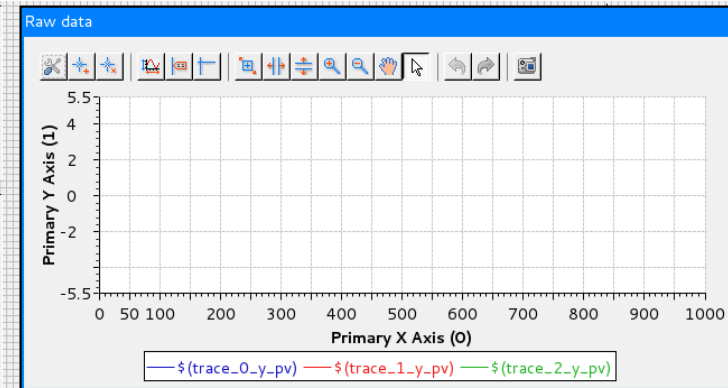
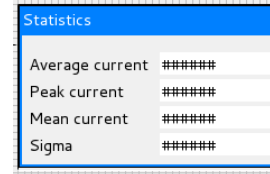
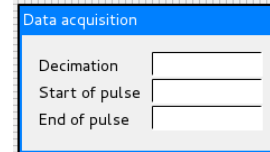
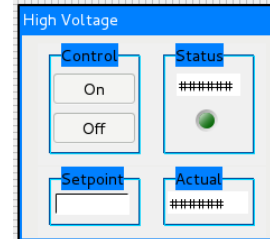
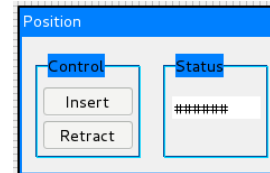
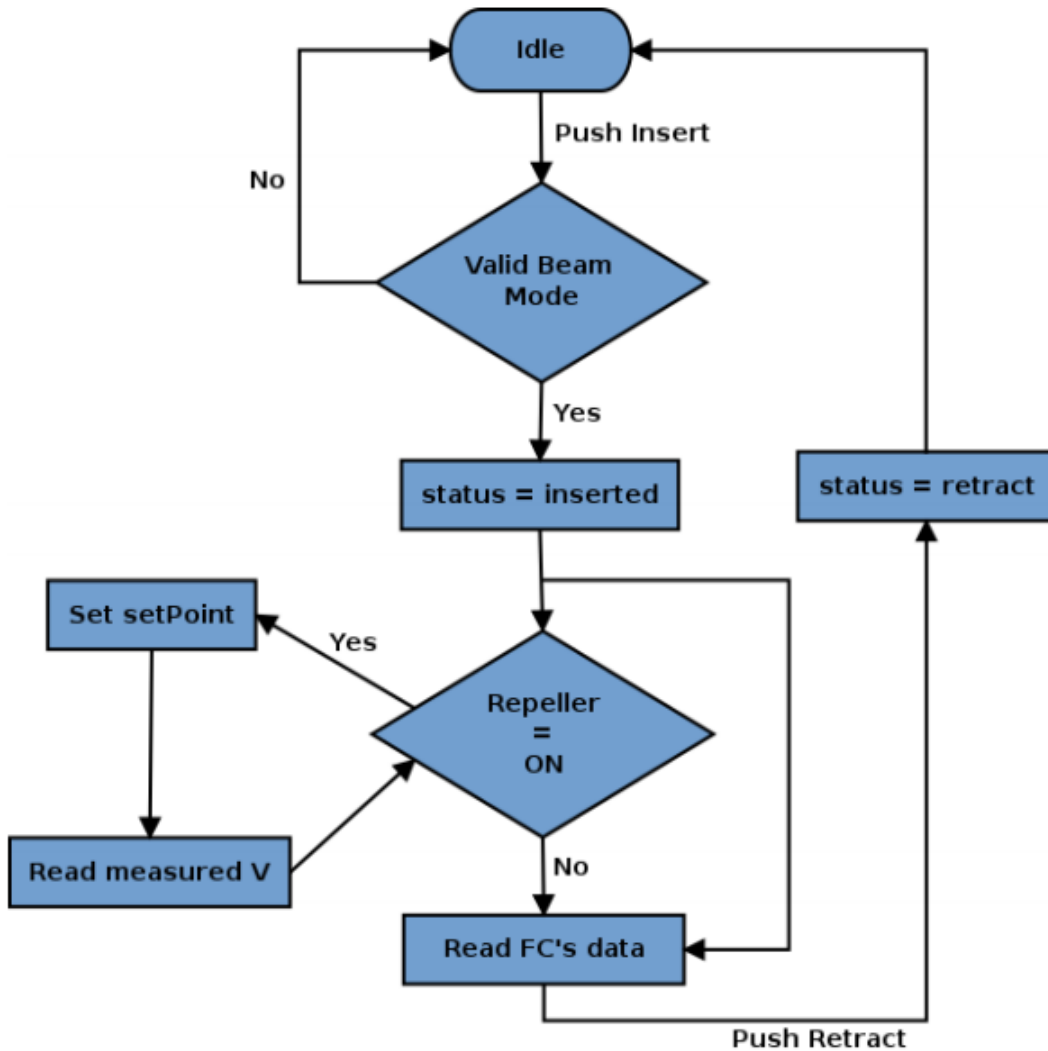
# HW Description

MEBT FC scheme





# Control Flow Diagram

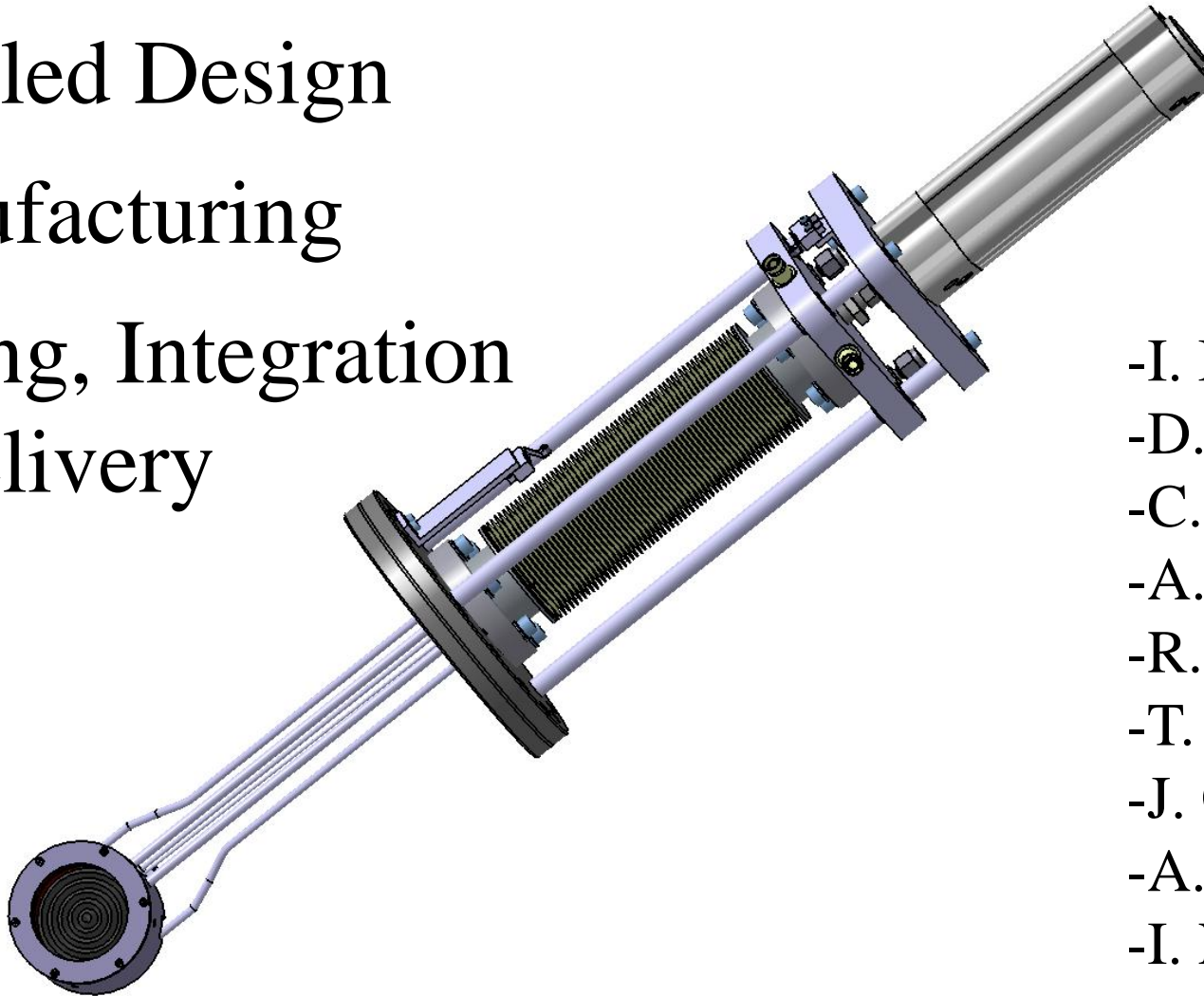


# Summary

- .Introduction
- .Conceptual Design
- .Mechanical Design
- .Signal Conditioning
- .EEE Integration & IOC
- .Conclusions

# Conclusions

- Conceptual Design
- Detailed Design
- Manufacturing
- Testing, Integration & Delivery



-I. Bustinduy  
-D. de Cos  
-C. de la Cruz  
-A. Milla  
-R. Miracoli  
-T. Mora  
-J. Ortega  
-A. R. Páramo  
-I. Rueda

# Conclusions

Thank you for your attention